



NOTES.  
 1. 適合ハウジング: 501189-\*\*\*\*  
 APPLICABLE HOUSING: 501189-\*\*\*\*  
 2. メッキ仕様  
 PLATING  
 金メッキ: 0.1 μmMIN.  
 Au PLATING  
 ニッケルメッキ (下地): 1.0 μmMIN.  
 NI PLATING (UNDER PLATING)

501193-0100	バラ状 LOOSE
501193-0000	連鎖状 CHAIN
MATERIAL NO.	端子形状 FORM

MATERIAL リン青銅 PHOSPHOR BRONZE ±0.12 FINISH SEE NOTE WIRE RANGE AWG#28-32 INS. RANGE φ 0.4-0.8	REVISED IEC NO. J2005-0329 DRAWN: NYOSHIDA 2004/11/02 CHKD: MYAGI 2004/11/02 APPR: ANODA 2004/11/12 DESCRIPTION A	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 20:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
		10 UNDER ±0.2 10 OVER 30 UNDER ±0.25 30 OVER ±0.3 ANGULAR ±3° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DRAWN BY NYOSHIDA DATE 2004/04/03 CHECKED BY MYAGI DATE 2004/04/03 APPROVED BY MIYAZAWA DATE 2004/04/03 MATERIAL NO. SEE CHART	TITLE 1.0 WIRE TO BOARD CONN. CRIMP REC TERMINAL	MOLEX INCORPORATED DOCUMENT NO. SD-501193-001	SHEET NO. 1 OF 1		